


## APPLICATION DATA SHEET

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<b>Title of Invention</b>	[STRUCTURE OF A SUBSTRATE FOR A HIGH DENSITY SEMICONDUCTOR PACKAGE]	
Application Type : regular, utility Attorney Docket Number : 10517-US-PA		
Correspondence address: Customer Number: 31561 		
Continuing Data: This is a Non-Provisional of US application number 60/319,909, filed 2003-01-28 , now pending.		
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